

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 196273US-0 CONT		SERIAL NO. New Rule 1.53(b) Continuation Application	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Ende SHAN, et al.			
				FILING DATE HEREWITH		GROUP	

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U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
<i>SL</i>	AA	5,270,255	12/14/93	Wong			
<i>SL</i>	AB	5,108,951	04/28/92	Chen, et al.			
<i>SL</i>	AC	5,358,616	10/25/94	Ward			
<i>SL</i>	AD	5,600,182	02/04/97	Schinella, et al.			
<i>SL</i>	AE	5,693,564	12/22/94	Yu			
<i>SL</i>	AF	5,582,679	12/10/96	Liajun, et al.			
<i>SL</i>	AG	5,665,659	09/09/97	Lee, et al.			
<i>SL</i>	AH	5,158,933	10/27/92	Holtz, et al.			
<i>SL</i>	AI	4,970,176	11/13/90	Tracy, et al.			
<i>SL</i>	AJ	5,731,245	10/28/96	Joshi, et al.			
<i>SL</i>	AK	5,443,995	08/22/95	Nulman			
<i>SL</i>	AL	5,911,113	06/08/99	Yao, et al.			
<i>SL</i>	AM	5,374,592	12/20/94	MacNaughton, et al.			
<i>SL</i>	AN	5,371,042	12/06/94	Ong			

FOREIGN PATENT DOCUMENTS					
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO
	AO				
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	AT				
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	AV				

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)	
<i>SL</i>	AW <u>Elsevier Science S.A.</u> , Thin Solid Films 253 (1994) 367-371, "A1 planarization processes for multilayer metallization of quarter micrometer devices", Zheng Xu,
<i>SL</i>	AX <u>Electronic Engineering Times (EETIMES)</u> , Issue 939, February 3, 1997, "A1 hits sub-0.25 micron vias", Title Page w. page 37 and page 42
<i>SL</i>	AY <u>Semiconductor International</u> , August 1994, "The Interconnect Challenge: Filling Small, High Aspect Ratio Contact Holes"
<i>SL</i>	AZ SPIE Vol. 2335, pp. 70-79, Invited Paper, Applied Material, Inc., PVD Division, Santa Clara, CA 95054, "Planar Multilevel Metallization Technologies for ULSI Devices", Zheng Xu,

Examiner <i>Lamardo Toledo</i>	Date Considered <i>1/24/2002</i>
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*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
<i>TAJ</i>	AAA	5,378,660	01/03/95	Ngan, et al.			
<i>TAJ</i>	AAB	5,108,570	04/28/92	Wang			
	AC						
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	AX						
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Examiner <i>Lernando Toledo</i>					Date Considered <i>1/24/02</i>		
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